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Understanding <u>Embedded - CPLDs (Complex Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	20 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	5000
Number of I/O	164
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	192-BPGA
Supplier Device Package	192-PGA (44.7x44.7)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7256egc192-20

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Feat	ures		
Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			✓
JTAG BST circuitry			√ (1)
Open-drain output option			✓
Fast input registers		✓	✓
Six global output enables		✓	✓
Two global clocks		✓	✓
Slew-rate control		✓	✓
MultiVolt interface (2)	✓	✓	✓
Programmable register	✓	✓	✓
Parallel expanders	✓	✓	✓
Shared expanders	✓	✓	✓
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	✓	✓	✓

Notes:

- (1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
- (2) The MultiVolt I/O interface is not available in 44-pin packages.

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. The MAX 7000 architecture easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000 devices are available in a wide range of packages, including PLCC, PGA, PQFP, RQFP, and TQFP packages. See Table 5.

Table 5. M.	AX 7000) Maxim	um Use	r I/O Pii	ıs N	ote (1)						
Device	44- Pin PLCC	44- Pin PQFP	44- Pin TQFP	68- Pin PLCC	84- Pin PLCC	100- Pin PQFP	100- Pin TQFP	160- Pin PQFP	160- Pin PGA	192- Pin PGA	208- Pin PQFP	208- Pin RQFP
EPM7032	36	36	36									
EPM7032S	36		36									
EPM7064	36		36	52	68	68						
EPM7064S	36		36		68		68					
EPM7096				52	64	76						
EPM7128E					68	84		100				
EPM7128S					68	84	84 (2)	100				
EPM7160E					64	84		104				
EPM7160S					64		84 (2)	104				
EPM7192E								124	124			
EPM7192S								124				
EPM7256E								132 (2)		164		164
EPM7256S											164 (2)	164

Notes:

- When the JTAG interface in MAX 7000S devices is used for either boundary-scan testing or for ISP, four I/O pins become JTAG pins.
- (2) Perform a complete thermal analysis before committing a design to this device package. For more information, see the Operating Requirements for Altera Devices Data Sheet.

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

Figure 6. Parallel Expanders

Unused product terms in a macrocell can be allocated to a neighboring macrocell.

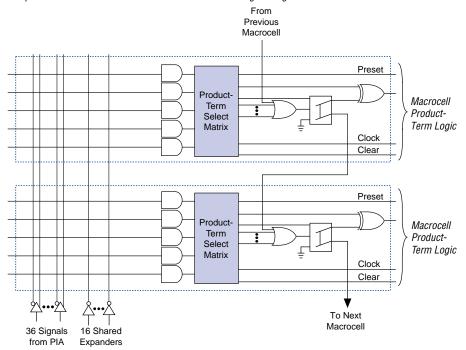
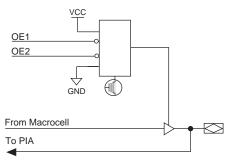
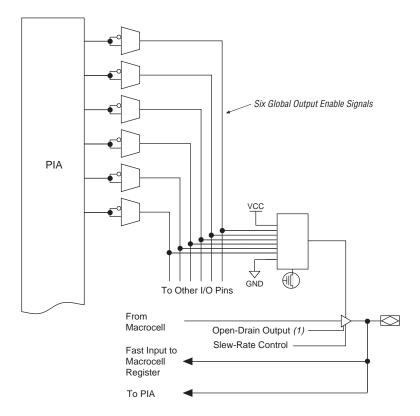


Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices



MAX 7000E & MAX 7000S Devices



Note:

(1) The open-drain output option is available only in MAX 7000S devices.

Design Security

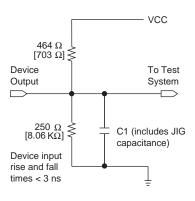
All MAX 7000 devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a proprietary design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

Generic Testing

Each MAX 7000 device is functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 10. Test patterns can be used and then erased during early stages of the production flow.

Figure 10. MAX 7000 AC Test Conditions

Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground. significant reductions in observable noise immunity can result. Numbers in brackets are for 2.5-V devices and outputs. Numbers without brackets are for 3.3-V devices and outputs.



QFP Carrier & Development Socket

MAX 7000 and MAX 7000E devices in QFP packages with 100 or more pins are shipped in special plastic carriers to protect the QFP leads. The carrier is used with a prototype development socket and special programming hardware available from Altera. This carrier technology makes it possible to program, test, erase, and reprogram a device without exposing the leads to mechanical stress.



For detailed information and carrier dimensions, refer to the *QFP Carrier & Development Socket Data Sheet*.



MAX 7000S devices are not shipped in carriers.

Symbol	Parameter	Conditions	Min	Max	Unit
V _{IH}	High-level input voltage		2.0	V _{CCINT} + 0.5	V
V _{IL}	Low-level input voltage		-0.5 (8)	0.8	V
V _{OH}	5.0-V high-level TTL output voltage	I _{OH} = -4 mA DC, V _{CCIO} = 4.75 V (10)	2.4		V
	3.3-V high-level TTL output voltage	I _{OH} = -4 mA DC, V _{CCIO} = 3.00 V (10)	2.4		V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V} (10)$	V _{CCIO} - 0.2		V
V _{OL}	5.0-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 4.75 V (11)		0.45	V
	3.3-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 3.00 V (11)		0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V}(11)$		0.2	V
lı	Leakage current of dedicated input pins	$V_I = -0.5 \text{ to } 5.5 \text{ V } (11)$	-10	10	μА
l _{OZ}	I/O pin tri-state output off-state current	$V_I = -0.5 \text{ to } 5.5 \text{ V } (11), (12)$	-40	40	μА

Table 1	Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices Note (13)									
Symbol	Parameter	Parameter Conditions								
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		12	pF					
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		12	pF					

Table 1	7. MAX 7000 5.0-V Device Capa	acitance: MAX 7000E Devices Note	(13)		
Symbol	Parameter	Conditions	Min	Max	Unit
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		15	pF
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		15	pF

Table 1	Table 18. MAX 7000 5.0-V Device Capacitance: MAX 7000S Devices Note (13)									
Symbol	Parameter	Conditions	Min	Max	Unit					
C _{IN}	Dedicated input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		10	pF					
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		10	pF					

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input voltage on I/O pins is –0.5 V and on 4 dedicated input pins is –0.3 V. During transitions, the inputs may undershoot to –2.0 V or overshoot to 7.0 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) V_{CC} must rise monotonically.
- (5) The POR time for all 7000S devices does not exceed 300 μs. The sufficient V_{CCINT} voltage level for POR is 4.5 V. The device is fully initialized within the POR time after V_{CCINT} reaches the sufficient POR voltage level.
- (6) 3.3-V I/O operation is not available for 44-pin packages.
- (7) The V_{CCISP} parameter applies only to MAX 7000S devices.
- (8) During in-system programming, the minimum DC input voltage is –0.3 V.
- (9) These values are specified under the MAX 7000 recommended operating conditions in Table 14 on page 26.
- (10) The parameter is measured with 50% of the outputs each sourcing the specified current. The I_{OH} parameter refers to high-level TTL or CMOS output current.
- (11) The parameter is measured with 50% of the outputs each sinking the specified current. The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current.
- (12) When the JTAG interface is enabled in MAX 7000S devices, the input leakage current on the JTAG pins is typically -60 uA.
- (13) Capacitance is measured at 25° C and is sample-tested only. The OE1 pin has a maximum capacitance of 20 pF.

Figure 11 shows the typical output drive characteristics of MAX 7000 devices.

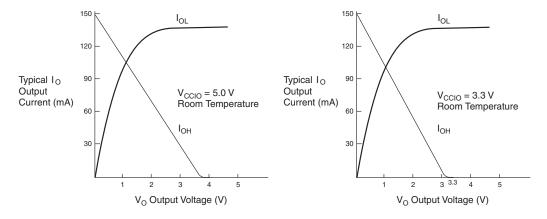
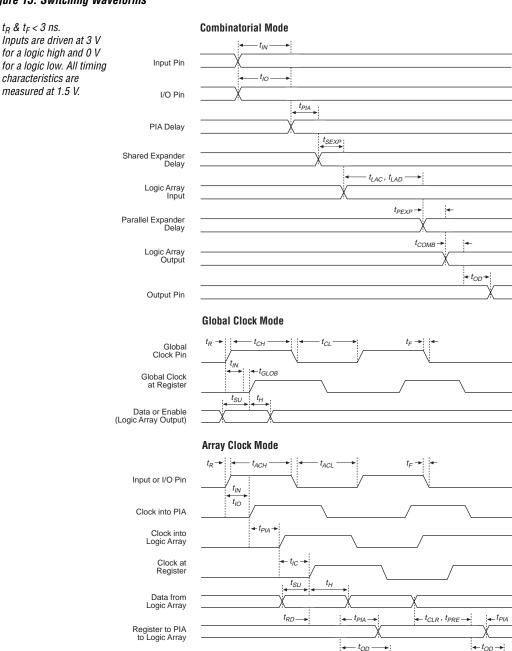


Figure 11. Output Drive Characteristics of 5.0-V MAX 7000 Devices

Timing Model

MAX 7000 device timing can be analyzed with the Altera software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 12. MAX 7000 devices have fixed internal delays that enable the designer to determine the worst-case timing of any design. The Altera software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for a device-wide performance evaluation.

Figure 13. Switching Waveforms



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Register Output to Pin

Tables 19 through 26 show the MAX 7000 and MAX 7000E AC operating conditions.

Symbol	Parameter	Conditions	-6 Speed Grade		-7 Spee	d Grade	Unit
			Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{SU}	Global clock setup time		5.0		6.0		ns
t _H	Global clock hold time		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	2.5		3.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns
t _{CH}	Global clock high time		2.5		3.0		ns
t _{CL}	Global clock low time		2.5		3.0		ns
t _{ASU}	Array clock setup time		2.5		3.0		ns
t _{AH}	Array clock hold time		2.0		2.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns
t _{ACH}	Array clock high time		3.0		3.0		ns
t _{ACL}	Array clock low time		3.0		3.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	3.0		3.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.6		8.0	ns
f _{CNT}	Maximum internal global clock frequency	(5)	151.5		125.0		MHz
t _{ACNT}	Minimum array clock period			6.6		8.0	ns
f _{ACNT}	Maximum internal array clock frequency	(5)	151.5		125.0		MHz
f _{MAX}	Maximum clock frequency	(6)	200		166.7		MHz

Table 2	9. EPM7064\$ External Timi	ing Parameters	(Part 2	2 of 2)	No	te (1)					
Symbol	Parameter	Conditions	Conditions Speed Grade								Unit
			-	5	-	6	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.1		8.0		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.1		8.0		10.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Table 3	O. EPM7064\$ Internal Tim	ing Parameters	(Part	1 of 2)	No	te (1)					
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	5	-	6	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{FIN}	Fast input delay			2.2		2.6		1.0		1.0	ns
t _{SEXP}	Shared expander delay			3.1		3.8		4.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.9		1.1		0.8		0.8	ns
t_{LAD}	Logic array delay			2.6		3.2		3.0		5.0	ns
t _{LAC}	Logic control array delay			2.5		3.2		3.0		5.0	ns
t _{IOE}	Internal output enable delay			0.7		0.8		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		2.5		2.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t _{SU}	Register setup time		0.8		1.0		3.0		2.0		ns
t _H	Register hold time		1.7		2.0		2.0		3.0		ns

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	5	-	6	-	7	-1	10	-
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{FSU}	Register setup time of fast input		1.9		1.8		3.0		3.0		ns
t _{FH}	Register hold time of fast input		0.6		0.7		0.5		0.5		ns
t _{RD}	Register delay			1.2		1.6		1.0		2.0	ns
t _{COMB}	Combinatorial delay			0.9		1.0		1.0		2.0	ns
t _{IC}	Array clock delay			2.7		3.3		3.0		5.0	ns
t _{EN}	Register enable time			2.6		3.2		3.0		5.0	ns
t_{GLOB}	Global control delay			1.6		1.9		1.0		1.0	ns
t _{PRE}	Register preset time			2.0		2.4		2.0		3.0	ns
t _{CLR}	Register clear time			2.0		2.4		2.0		3.0	ns
t _{PIA}	PIA delay	(7)		1.1		1.3		1.0		1.0	ns
t_{LPA}	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 3	11. EPM7128\$ External Time	ing Parameters	: No	te (1)							
Symbol	Parameter	Conditions				Speed	Grade)			Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t _{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 33 and 34 show the EPM7160S AC operating conditions.

Table 3	33. EPM7160S External Timi	ng Parameters	(Part	1 of 2)	No	nte (1)						
Symbol	Parameter	Conditions	Conditions Speed Grade									
			-6		-7		-10		-15			
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns	
t _{SU}	Global clock setup time		3.4		4.2		7.0		11.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns	
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns	
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns	
t _{ASU}	Array clock setup time		0.9		1.1		2.0		4.0		ns	
t _{AH}	Array clock hold time		1.7		2.1		3.0		4.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns	
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns	
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns	
t _{CNT}	Minimum global clock period			6.7		8.2		10.0		13.0	ns	
f _{CNT}	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz	

Table 3	Table 33. EPM7160S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade									
			-	-6 -7				-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns	
f _{ACNT}	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz	
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz	

Table 3	4. EPM7160\$ Internal Tim	ing Parameters	(Part	1 of 2)	No	te (1)						
Symbol	Parameter	Conditions	Speed Grade									
			-6		-7		-10		-15			
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns	
t _{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns	
t _{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns	
t _{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns	
t _{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns	
t_{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns	
t _{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns	
t _{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns	
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns	
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns	
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns	
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns	
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns	
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns	
t _{SU}	Register setup time		1.0		1.2		2.0		4.0		ns	
t _H	Register hold time		1.6		2.0		3.0		4.0		ns	
t _{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns	
t_{RD}	Register delay			1.3		1.6		2.0		1.0	ns	
t _{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns	
t _{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns	
t _{EN}	Register enable time			2.8		3.4		5.0		6.0	ns	
t _{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns	
t _{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns	

Table 3	Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2)Note (1)											
Symbol	Parameter	Conditions		Speed Grade								
			-	-6 -7				-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns	
t _{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns	
t _{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns	

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 35. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-7		-10		-15				
			Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns		
t _H	Global clock hold time		0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns		
t _{CH}	Global clock high time		3.0		4.0		5.0		ns		
t _{CL}	Global clock low time		3.0		4.0		5.0		ns		
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns		

Tables 37 and 38 show the EPM7256S AC operating conditions.

Symbol	Parameter	Conditions	Speed Grade							
Oymboi	i arameter			7		10		15	Unit	
	Insult to your resistant of output			Min Max		Max	Min	Max		
4			IVIIII	7.5	Min	10.0	IVIIII	15.0		
t _{PD1}	Input to non-registered output I/O input to non-registered output	C1 = 35 pF C1 = 35 pF		7.5		10.0		15.0	ns ns	
t _{SU}	Global clock setup time		3.9		7.0		11.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns	
t _{CH}	Global clock high time		3.0		4.0		5.0		ns	
t _{CL}	Global clock low time		3.0		4.0		5.0		ns	
t _{ASU}	Array clock setup time		0.8		2.0		4.0		ns	
t _{AH}	Array clock hold time		1.9		3.0		4.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns	
t _{ACH}	Array clock high time		3.0		4.0		6.0		ns	
t _{ACL}	Array clock low time		3.0		4.0		6.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns	
t _{CNT}	Minimum global clock period			7.8		10.0		13.0	ns	
f _{CNT}	Maximum internal global clock frequency	(4)	128.2		100.0		76.9		MHz	
t _{ACNT}	Minimum array clock period			7.8		10.0		13.0	ns	
f _{ACNT}	Maximum internal array clock frequency	(4)	128.2		100.0		76.9		MHz	
f _{MAX}	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz	

Symbol	Parameter	Conditions	Speed Grade							
			-7		-10		-15		1	
			Min	Max	Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns	
t _{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns	
t _{FIN}	Fast input delay			3.4		1.0		2.0	ns	
t _{SEXP}	Shared expander delay			3.9		5.0		8.0	ns	
t_{PEXP}	Parallel expander delay			1.1		0.8		1.0	ns	
t_{LAD}	Logic array delay			2.6		5.0		6.0	ns	
t _{LAC}	Logic control array delay			2.6		5.0		6.0	ns	
t _{IOE}	Internal output enable delay			0.8		2.0		3.0	ns	
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns	
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns	
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns	
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns	
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns	
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns	
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns	
t _{SU}	Register setup time		1.1		2.0		4.0		ns	
t _H	Register hold time		1.6		3.0		4.0		ns	
t _{FSU}	Register setup time of fast input		2.4		3.0		2.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.5		1.0		ns	
t_{RD}	Register delay			1.1		2.0		1.0	ns	
t _{COMB}	Combinatorial delay			1.1		2.0		1.0	ns	
t _{IC}	Array clock delay			2.9		5.0		6.0	ns	
t_{EN}	Register enable time			2.6		5.0		6.0	ns	
t _{GLOB}	Global control delay			2.8		1.0		1.0	ns	
t _{PRE}	Register preset time			2.7		3.0		4.0	ns	
t _{CLR}	Register clear time			2.7		3.0		4.0	ns	
t _{PIA}	PIA delay	(7)		3.0		1.0		2.0	ns	
t _{LPA}	Low-power adder	(8)		10.0	İ	11.0		13.0	ns	

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Power Consumption

Supply power (P) versus frequency (f_{MAX} in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The P_{IO} value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note* 74 (*Evaluating Power for Altera Devices*).

The I_{CCINT} value, which depends on the switching frequency and the application logic, is calculated with the following equation:

$$I_{CCINT} =$$

$$A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times tog_{USED}$$

The parameters in this equation are shown below:

 MC_{TON} = Number of macrocells with the Turbo Bit option turned on,

as reported in the MAX+PLUS II Report File (.rpt)

 MC_{DEV} = Number of macrocells in the device

MC_{USED} = Total number of macrocells in the design, as reported

in the MAX+PLUS II Report File (.rpt)

 f_{MAX} = Highest clock frequency to the device

tog_{LC} = Average ratio of logic cells toggling at each clock

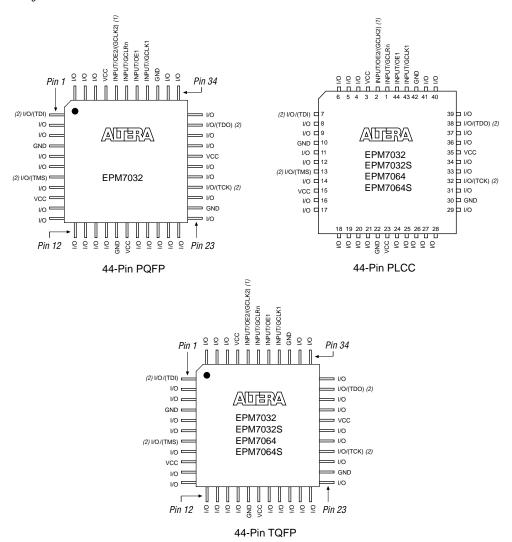
(typically 0.125)

A, B, C = Constants, shown in Table 39

Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



Notes:

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7 supersedes information published in previous versions. The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

Version 6.7

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.7:

Reference to AN 88: Using the Jam Language for ISP & ICR via an Embedded Processor has been replaced by AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

Version 6.6

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.6:

- Added Tables 6 through 8.
- Added "Programming Sequence" section on page 17 and "Programming Times" section on page 18.

Version 6.5

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.5:

Updated text on page 16.

Version 6.4

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.4:

Added Note (5) on page 28.

Version 6.3

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.3:

■ Updated the "Open-Drain Output Option (MAX 7000S Devices Only)" section on page 20.